

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2632hts8-hi10#trmpbf

(Engineering Calculation)

TSOT-23

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TOTAL MASS (g) : 0.012478

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.000710 | 1000000 | 56901.5546875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.004582 | 975000 | 367215.40625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000113 | 24000 | 9056.16308594 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000001 | 300 | 80.1430358887 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000003 | 700 | 240.429122925 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.004699 | 1000000 | 376592.125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000663 | 1000000 | 53109.9882812 | | |
| | | External Plating Total: | | | | 0.000663 | 1000000 | 53109.9882812 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000080 | 1000000 | 6411.44287109 | | |
| Internal Plating Total: | | | | 0.000080 | 1000000 | 6411.44287109 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000206 | 800000 | 16509.4667969 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000051 | 200000 | 4087.29492188 | | |
| Die Attach Total: | | | | 0.000257 | 1000000 | 20596.7617188 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.000347 | 58000 | 27809.6328125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.005322 | 890000 | 426521.25 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000299 | 50000 | 23962.7675781 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000012 | 2000 | 961.716491699 | | |
| | | Encapsulation Total: | | | | 0.005980 | 1000000 | 479255.34375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000089 | 1000000 | 7132.73046875 | | |
| | | | | | TOTAL MASS (g) : | 0.012478 | | |